



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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Email & Skype: info@chipsmall.com Web: www.chipsmall.com

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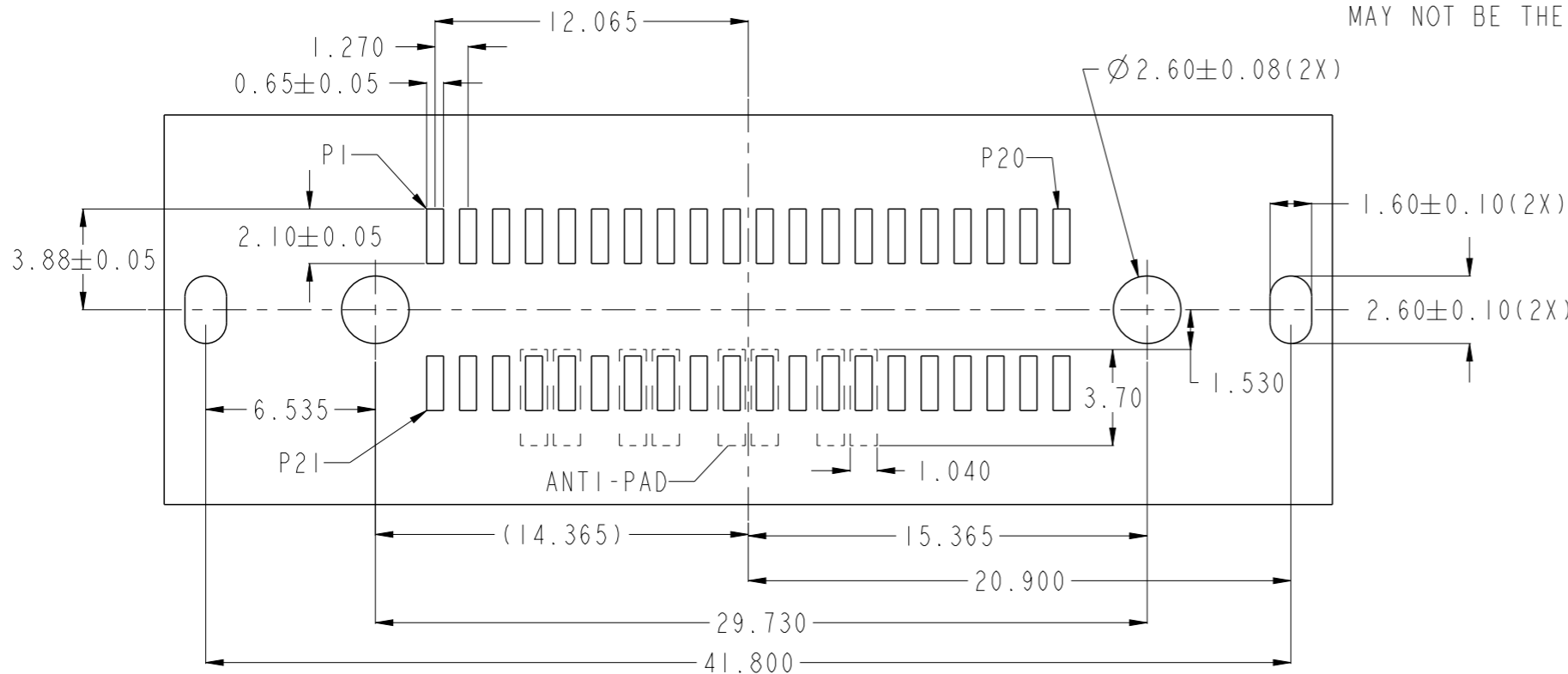


PRODUCT No.	PICK UP CAP	PLATING SPEC	PACKAGING
10121749-001LF	NO	2A	TRAY
10121749-001TRLF	NO		TAPE & REEL
10121749-001CLF	YES		TRAY
10121749-001C-TRLF	YES		TAPE & REEL
10121749-101LF	NO	2B	TRAY
10121749-101TRLF	NO		TAPE & REEL
10121749-101CLF	YES		TRAY
10121749-101C-TRLF	YES		TAPE & REEL
10121749-002LF	NO	2A	TRAY
10121749-002TRLF	NO		TAPE & REEL
10121749-002CLF	YES		TRAY
10121749-002C-TRLF	YES		TAPE & REEL

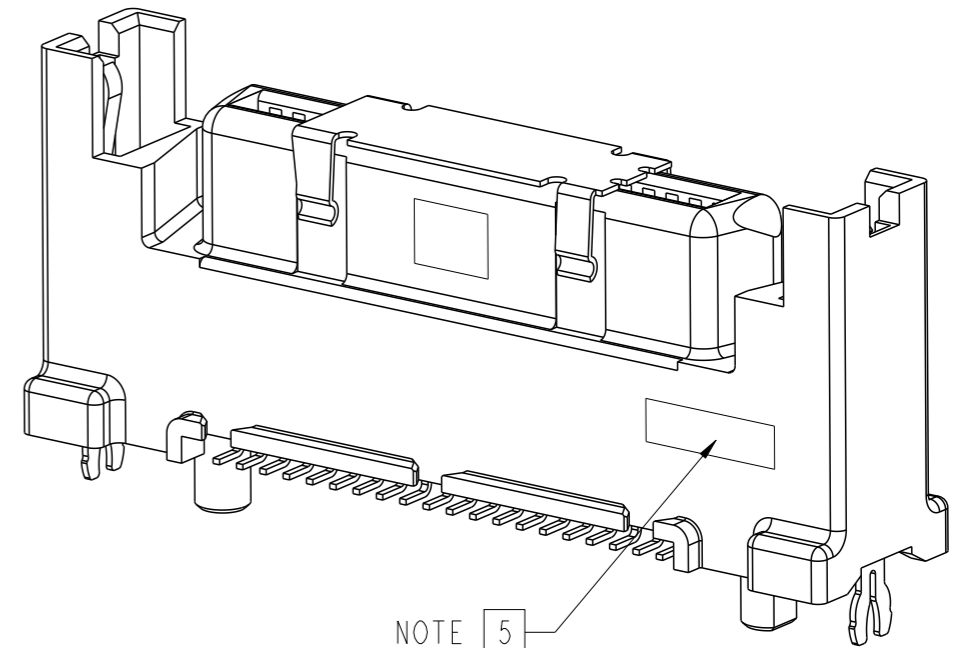


NOTES:

- MATERIALS:
HOUSING : HIGH TEMPERATURE THERMOPLASTIC
CONTACTS : COPPER ALLOY
ESD CONTACTS : COPPER ALLOY
- PLATING SPECIFICATION:
A. CONTACTS : 1.27um/50u" MIN NICKEL UNDERPLATE
0.76um/30u" MIN GOLD AT CONTACT AREA
2.54um/100u" MIN TIN AT SOLDER TAIL
ESD CONTACTS : 1.27um/50u" MIN NICKEL UNDERPLATE
2.54um/100u" MIN TIN OVERALL
B. CONTACTS : 1.27um/50u" MIN NICKEL UNDERPLATE
0.76um/30u" MIN GXT PLATING AT CONTACT AREA
2.54um/100u" MIN TIN AT SOLDER TAIL
ESD CONTACTS : 1.27um/50u" MIN NICKEL UNDERPLATE
2.54um/100u" MIN TIN OVERALL
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260° PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED ON GS-47-0004.
- APPROXIMATE LOCATION FOR DATE CODE MARKING.
- A SYMBOL BE NEXT TO ANY DIMENSION, VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION.
- DRAWING OF PICK UP CAP IS FOR ILLUSTRATION PURPOSE ONLY, ACTUAL ORIENTATION MAY NOT BE THE SAME ON PRODUCT.

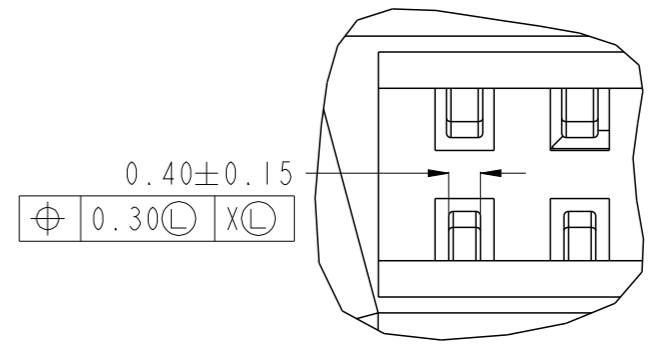
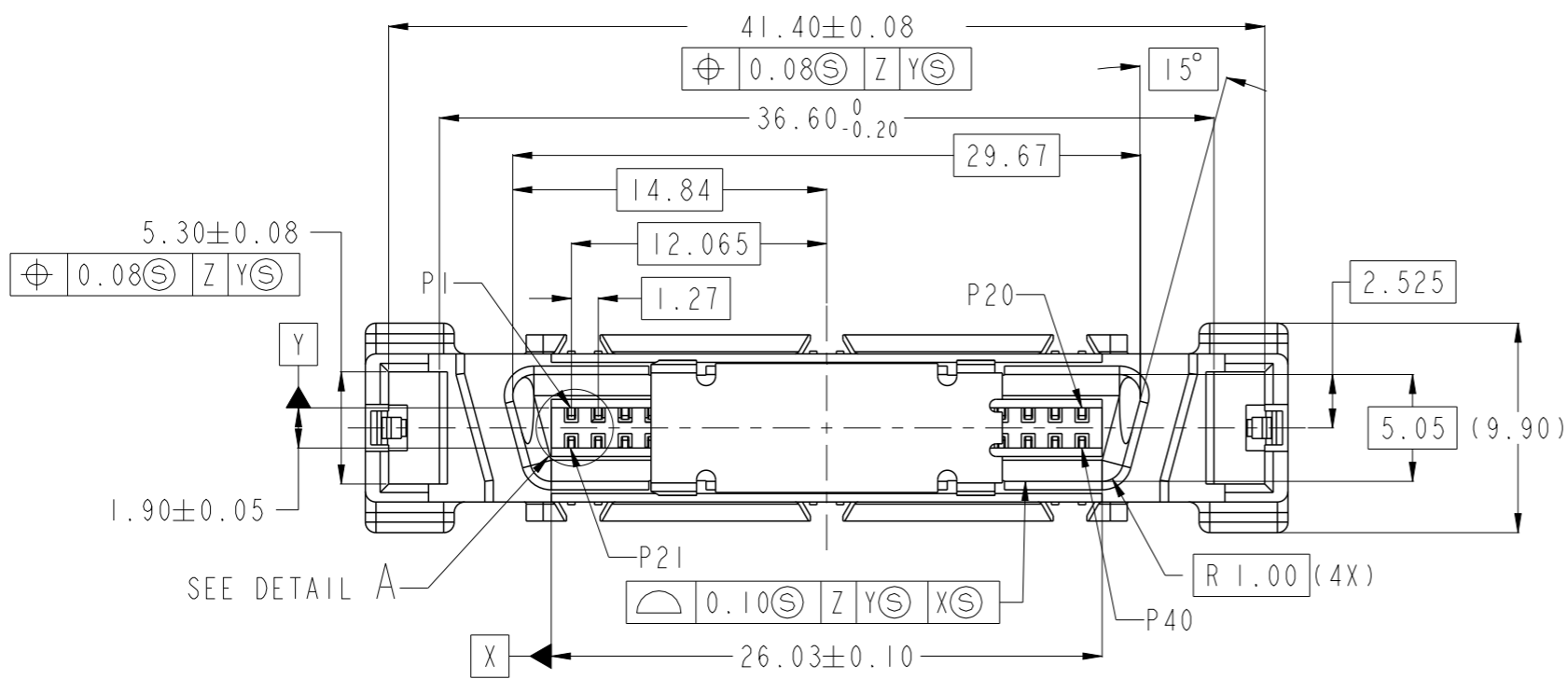


RECOMMENDED PCB LAYOUT
SCALE 4:1

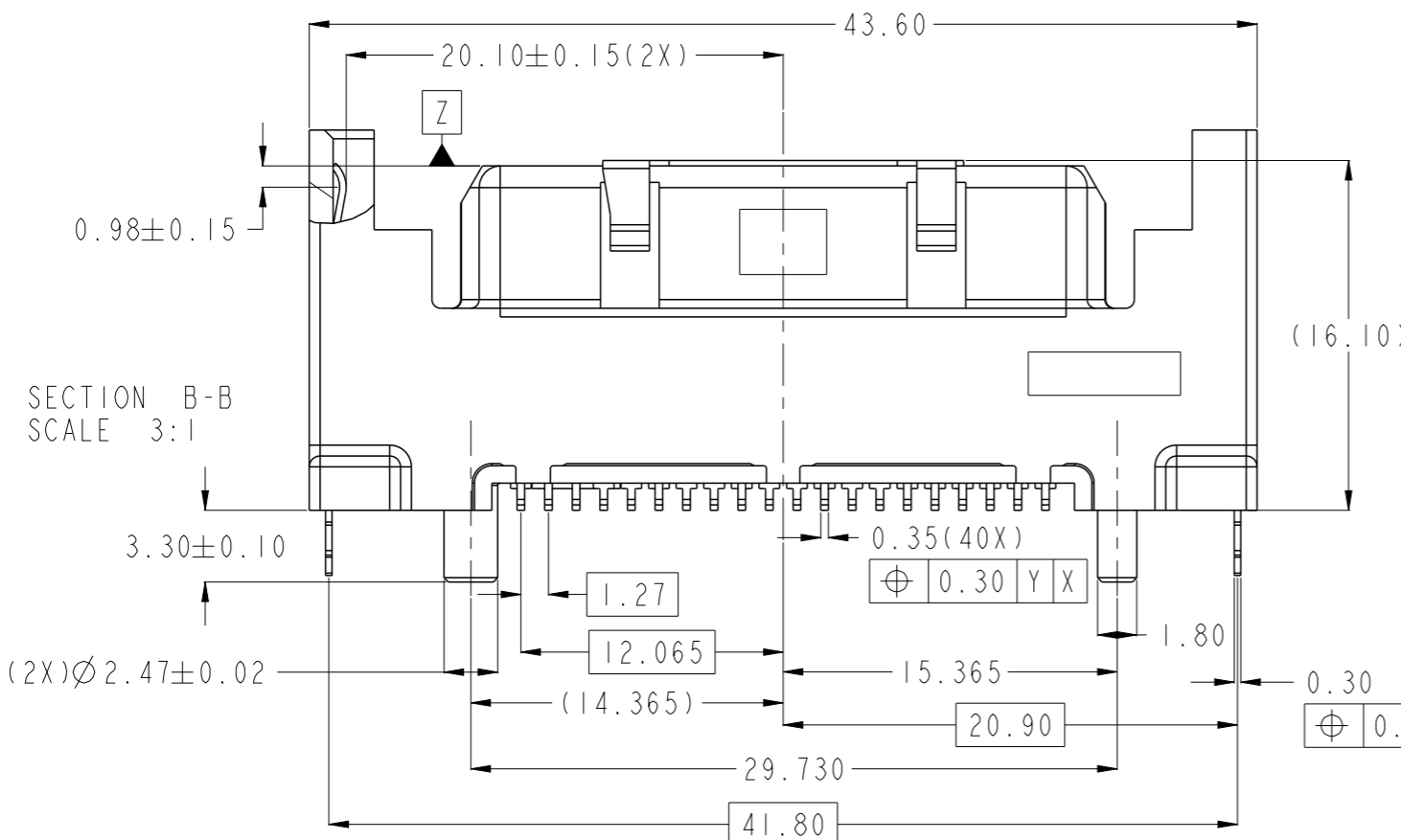


SCALE 3:1

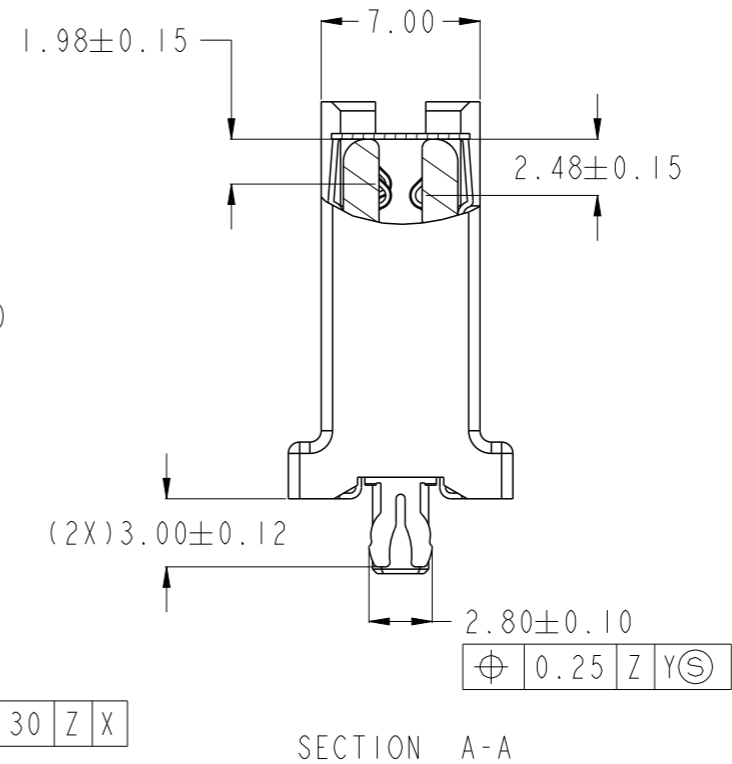
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tolerance std	TOLERANCES UNLESS OTHERWISE SPECIFIED	eng	Koon-Poh Tay	2016/05/03		← →	ecn no	ELX-S-23975-1			
-	-	chr	-	-			rel level	Released			
surface	linear	appr	Chen-Hong Tan	2016/05/26	product family	-	dwg no	10121749		rev	C
-	angular						Product - Customer Drw		sheet 1 of 2		



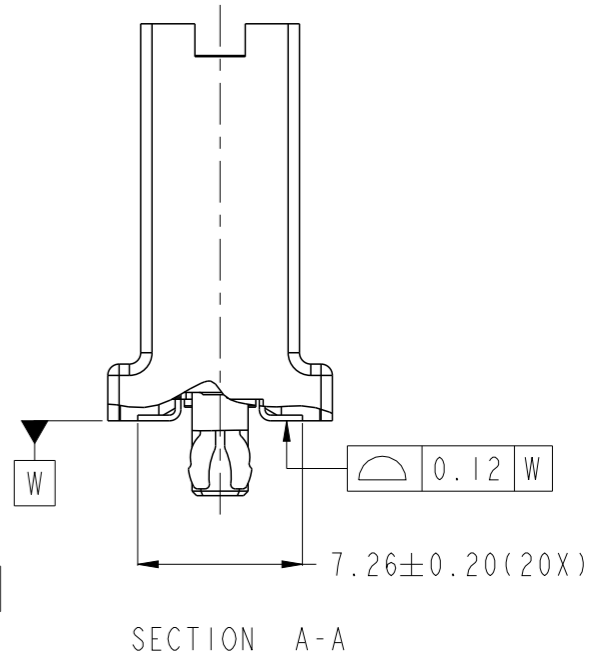
DETAIL A
SCALE 12:1



SECTION B-B
SCALE 3:1



SECTION A-A



SECTION A-A

spec ref	-	dr	Koon-Poh Tay	2013/04/23	projection	MM	size	A3	scale	1:1									
tolerance std	TOLERANCES UNLESS OTHERWISE SPECIFIED	eng	Koon-Poh Tay	2016/05/03			ecn no	ELX-S-23975-1	rel level	Released									
-		chr	-	app							Chen-Hong Tan	2016/05/26	product family	-					
surface	<table border="1"> <tr> <td>linear</td> <td>0.X</td> <td>±0.35</td> </tr> <tr> <td></td> <td>0.XX</td> <td>±0.25</td> </tr> <tr> <td></td> <td>0.XXX</td> <td>±0.13</td> </tr> <tr> <td>angular</td> <td>0°</td> <td>±2°</td> </tr> </table>	linear	0.X	±0.35		0.XX	±0.25		0.XXX	±0.13	angular	0°	±2°	Amphenol FCI		12G SCA-2 Receptacle 40 POS VERTICAL SMT EXT. HT.		dwg no 10121749	rev C
linear	0.X	±0.35																	
	0.XX	±0.25																	
	0.XXX	±0.13																	
angular	0°	±2°																	
-		cat. no.	-	Product - Customer Drw	sheet 2 of 2														